



IT-988GLTC

High Tg / Halogen Free / Ultra Low Loss Laminate & Prepreg

- Lower Dk (3.63 @ 10GHz) and Ultra low Df (0.0041 @ 10GHz) / 100G/400G Switch solution
- Very stable Dk-Df across frequency / Very Low CTE (1.7%)

Laminate properties

| Items | IPC TM-650 | | Typical Value | | Unit |
|--|---|-------|---|---|-----------------------|
| Peel Strength A. Low profile copper foil | 2.4.8 | | 3.5 | | lb/inch |
| Volume Resistivity | 2.5.17.1 | | 10 ¹⁰ | | MΩ-cm |
| Surface Resistivity | 2.5.17.1 | | 10 ¹⁰ | | MΩ |
| Moisture Absorption | 2.6.2.1 | | 0.12 | | % |
| Permittivity (Dk) A. 1GHz B. 2GHz C. 5GHz D. 10GHz | 2.5.5.9 2.5.5.13 2.5.5.13 2.5.5.13 | Note* | (55%/70%) 3.82/3.40 3.71/3.29 3.65/3.23 3.63/3.21 | 55% 3.83 3.83 3.83 | -- |
| Loss Tangent (Df) A. 1GHz B. 2GHz C. 5GHz D. 10GHz | 2.5.5.9 2.5.5.13 2.5.5.13 2.5.5.13 | Note* | (55%/70%) 0.0030/0.0024 0.0032/0.0026 0.0037/0.0030 0.0041/0.0033 | 55% 0.0032 0.0034 0.0034 0.0034 | -- |
| Flexural Strength A. Length direction B. Cross direction | 2.4.4 | | 475 415 | | N/mm ² |
| Thermal Stress 10 s at 288°C A. Unetched B. Etched | 2.4.13.1 | | Pass Pass | | Rating |
| Flammability | UL94 | | V-0 | | Rating |
| Glass Transition Temperature (TMA/DMA) | 2.4.25 | | 180/200 | | °C |
| Decomposition Temperature (5% W.L) | 2.4.24.6 | | 400 | | °C |
| X/Y Axis CTE (40°C to 125°C) | 2.4.41 | | 13/13 | | ppm/°C |
| Z-Axis CTE A. Alpha 1 B. Alpha 2 C. 50 °C to 260°C | 2.4.24 | | 35 190 1.7 | | ppm/°C ppm/°C % |
| Thermal Resistance A. T260 B. T288 | 2.4.24.1 | | >60 >60 | | Minutes Minutes |

Note*: The data presented above relates to the perpendicular dielectric parameters of the substrates. Resonators with different diameters have been used for the measurements of the disk samples.